

Technical Program at a Glance

Time	Tuesday • April 9		Wednesday • April 10		Thursday • April 11
8:00 AM	Opening & Keynote Begins at 7:50 a.m.		Parallel Session 3A ESD & Latchup + 4 papers	Parallel Session 3C Failure Analysis four papers	Plenary Session 5 on Process Induced Damage 1 invited review + 4 papers
8:25 AM					
8:50 AM	Plenary Session 1 on Non-Volatile Memories Six platform presentations		<i>extra time to check out the exhibits</i>		
9:15 AM					
9:40 AM					
10:05 AM Break					
10:30 AM			3B Compound Semiconductors I 3 papers	3D Product Reliability I 3 papers	Panel Discussion Product Qualification
10:55 AM					
11:20 AM					
11:45 AM	Dielectrics:ESREF Best Paper				
12:10 PM					
12:35 PM					
1:00 PM					
1:25 PM					
1:35 PM					
2:00 PM	Parallel Session 2A Dielectrics I four platform presentations	Parallel Session 2C MEMS 2 invited reviews + 2 papers	4A Compound Semiconductors II 3 papers	4C Product Reliability II 3 papers	SPECIAL TOPIC Irradiation (Germicidal) 3 papers
2:25 PM			4C Device &	4D Interconnects	
2:50 PM					Plenary Session 6 on Dielectrics II
3:15 PM					
3:40:00 PM Break					
4:05 PM	2B Hot Carriers five platform presentations	2D Assy/Pkg 3 invited reviews +1 paper	Process 5 papers	1 invited review + 5 papers'	5 papers
4:30 PM					
4:55 PM					
5:20 PM					
5:45 PM					
6:10 PM					
6:35 PM					
7:00 PM	Symposium Reception with Jack Kilby & 15 poster presentations		Workshops - 7:30 pm		

← April 7, Sunday NIGHT additional SER Workshop - Panel Discussion